

<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(selective with tungsten) and (contact with (hole or opening)) and ((hole or opening) with (align\$4 or regist\$6))	159	<u>L7</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(contact adj (hole or opening or via)) with ((overgrown or (growing adj over) or (nail adj head\$1) or overflow\$3)) and (align\$4 or misalign\$4)	15	<u>L6</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(contact adj (hole or opening or via)) with ((overgrown or (growing adj over) or (nail adj head\$1) or overflow\$3) with tungsten) and (align\$4 or misalign\$4)	1	<u>L5</u>
JPAB,EPAB,DWPI,TDBD	(contact adj (hole or opening or via)) with ((taper\$3 with upper) or (stepped adj portion)) and (align\$4 or misalign\$4)	4	<u>L4</u>
USPT	(contact adj (hole or opening or via)) with (taper\$3 with upper) and (align\$4 or misalign\$4)	26	<u>L3</u>
USPT	(contact adj (hole or opening)) with (stepped adj portion)	73	<u>L2</u>
USPT	(4970176 or 5071791 or 5147819).pn.	3	<u>L1</u>

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	78	DRAM and (selective with deposition with tungsten)	USPAT	2001/03/21 12:10
2	BRS	L2	324	(multi-level or multi-layer or (multiple adj layer\$3) or (multiple adj level\$1) or multilayer or multilevel) and tungsten and polysilicon and gate and (field adj oxide) and first and second and (align\$3 or misalign\$3) and (hole\$1 or opening\$1)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/03/21 13:15
3	BRS	L3	841	(selective with tungsten) same (contact (opening\$1 or hole\$1))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/03/21 13:17
4	BRS	L4	583	L3 and first and second	USPAT; EPO; JPO; Derwent; IBM TDB	2001/03/21 13:18
5	BRS	L6	9	L5 and ((taper\$3 or flar\$3 or (wet adj etch\$3) or widen\$3) with (align\$5 or misalign\$4))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/03/21 14:03
6	BRS	L7	5016	(open\$3 or via\$1 or hole\$1) with ((taper\$3 or flar\$3 or (wet adj etch\$3) or widen\$3) with (align\$5 or misalign\$4))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/03/21 13:40

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L8	5	L7 and (selective with tungsten)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/03/21 13:40
8	BRS	L5	380	L4 and (first with (fill\$3 or grow\$3 or deposit\$3)) and (second with (fill\$3 or grow\$3 or deposit\$3))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/03/21 13:49

<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(selective with tungsten) and (contact with (hole or opening)) and ((hole or opening) with (align\$4 or regist\$6))	159	<u>L7</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(contact adj (hole or opening or via)) with ((overgrown or (growing adj over) or (nail adj head\$1) or overflow\$3)) and (align\$4 or misalign\$4)	15	<u>L6</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(contact adj (hole or opening or via)) with ((overgrown or (growing adj over) or (nail adj head\$1) or overflow\$3) with tungsten) and (align\$4 or misalign\$4)	1	<u>L5</u>
JPAB,EPAB,DWPI,TDBD	(contact adj (hole or opening or via)) with ((taper\$3 with upper) or (stepped adj portion)) and (align\$4 or misalign\$4)	4	<u>L4</u>
USPT	(contact adj (hole or opening or via)) with (taper\$3 with upper) and (align\$4 or misalign\$4)	26	<u>L3</u>
USPT	(contact adj (hole or opening)) with (stepped adj portion)	73	<u>L2</u>
USPT	(4970176 or 5071791 or 5147819).pn.	3	<u>L1</u>